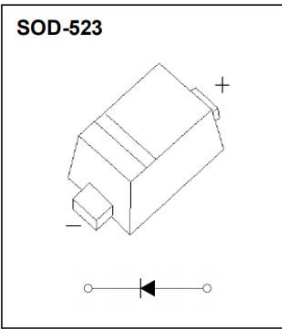


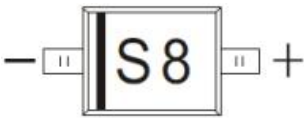
SOD-523 贴片塑封二极管

SOD-523 Plastic-Encapsulate Diodes

SOD-523



MARKING: S8



特征 Features

- 低正向电压差 Low Forward Voltage Drop
- 快速开关时间 Fast Switching Time
- 适用于自动插件的理想的表贴封装 Surface Mount Package Ideally Suited For Automatic Insertion

机械数据 Mechanical Data

- 封装: SOD-523 封装 SOD-523 Small Outline Plastic Package
- 极性: 色环端为负极 Polarity: Color band denotes cathode end
- 环氧树脂UL 易燃等级 Epoxy UL: 94V-0
- 安装位置: 任意 Mounting Position: Any

极限值和温度特性(TA = 25℃ 除非另有规定)

Maximum Ratings & Thermal Characteristics (Ratings at 25℃ ambient temperature unless otherwise specified.)

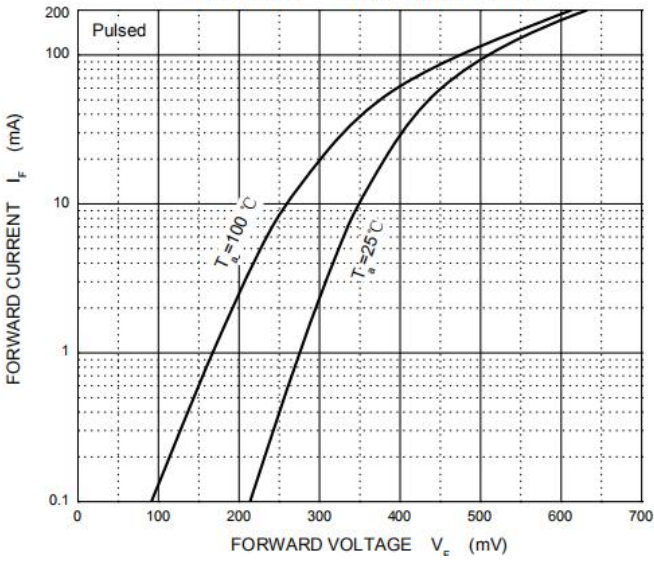
参数 Parameters	符号 Symbol	数值 Value	单位 Unit
直流阻断电压 DC Blocking Voltage	V _R	30	V
峰值重复反向电压 Peak Repetitive Reverse Voltage	V _{RRM}		
反向峰值工作电压 Working Peak Reverse Voltage	V _{RWM}		
均方根反向电压 RMS Reverse Voltage	V _{R(RMS)}	21	V
正向连续电流 Forward Continuous Current	I _{FM}	200	mA
尖峰正向重复电流 Repetitive Peak Forward Current @t<1.0s	I _{FRM}	500	mA
尖峰正向不重复浪涌电流 Non-repetitive Peak Forward Surge Current @t= 8.3ms	I _{FSM}	4.0	A
功率消耗 Power Dissipation	P _d	150	mW
结温 Junction temperature	T _j	125	℃
存储温度 Storage temperature range	T _{STG}	-55-+150	℃
热阻 Thermal Resistance from Junction to Ambient	R _{θJA}	667	℃/W

电特性 **Electrical Characteristics** (Ratings at 25℃ ambient temperature unless otherwise specified).

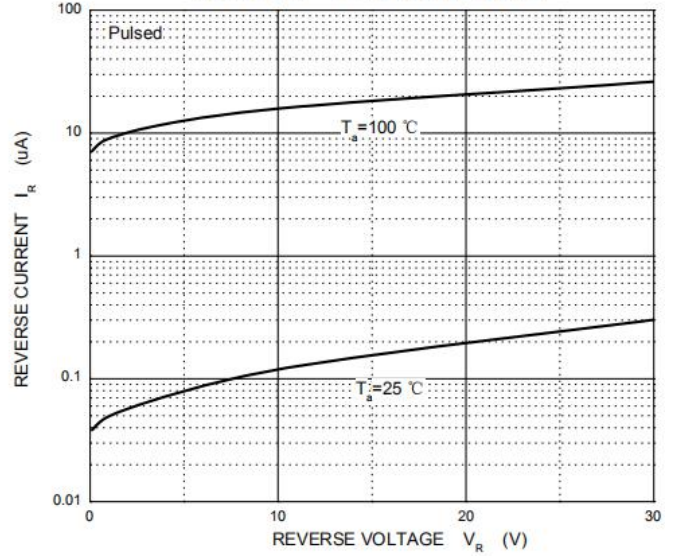
符号 Symbols	参数 Parameter	测试条件 Test Condition	界限 Limits		单位 Unit
			Min	Max	
V(BR)	反向击穿电压 Reverse Breakdown Voltage	I _R =10uA	30		V
I _R	反向漏电流 Reverse Current	V _R =25V	---	0.5	uA
V _F	正向电压 Forward Voltage	I _F =2mA	0.26	0.33	V
		I _F =15mA	---	0.45	
		I _F =200mA		1	
V _{FR}	正向恢复电压 Forward recovery voltage	I _F =10mA, t _r = 20ns		1.75	V
T _{RR}	反向恢复时间 Reverse Recovery Time	I _F = I _R = 10mA,	---	5	nS
		I _{rr} =0.1xI _R , R _L =100Ω			
C _T	端子间电容 Capacitance Between Terminals	V _R =1V, f=1MHZ	---	10	pF

典型特性 Typical Characteristics

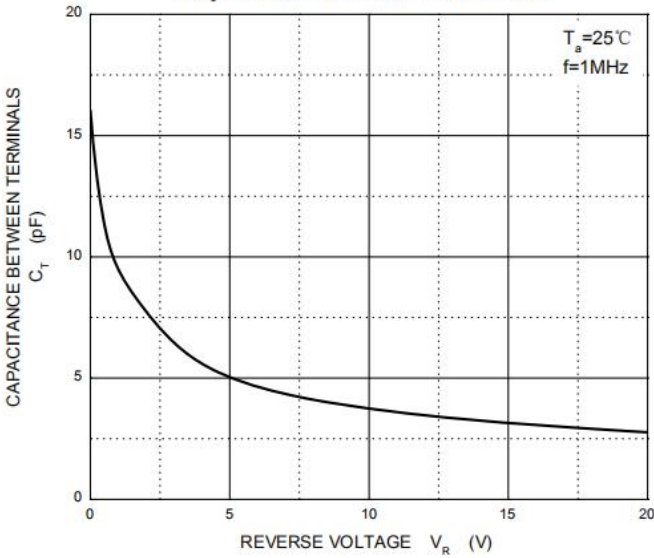
Forward Characteristics



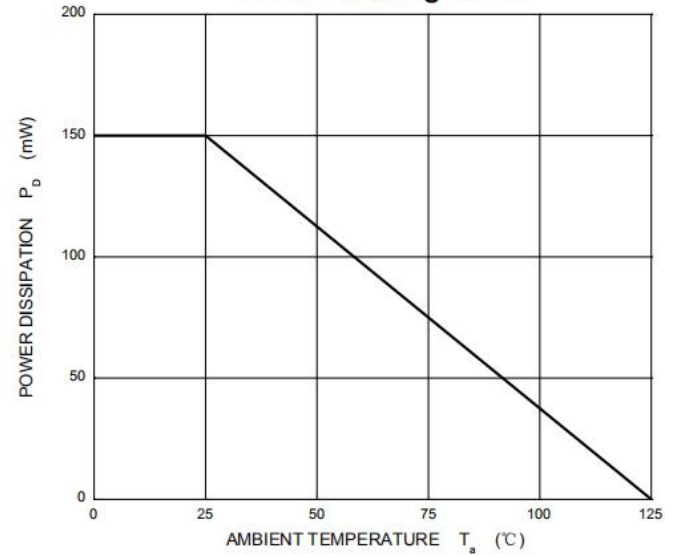
Reverse Characteristics



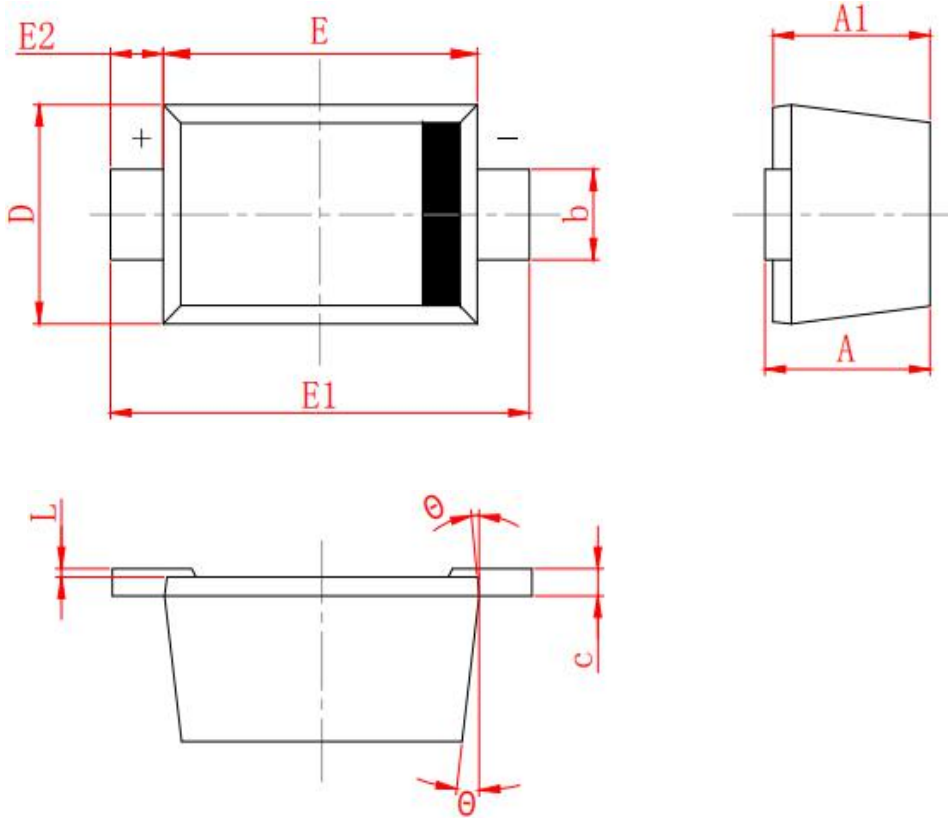
Capacitance Characteristics



Power Derating Curve

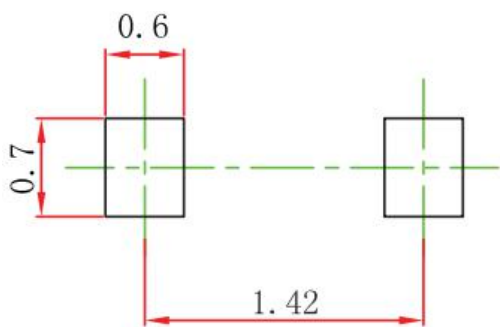


SOD-523封装外形尺寸图 SOD-523 Package Outline Dimensions



SYMBOL	MILLIMETER	
	MIN	MAX
A	0.530	0.730
A1	0.500	0.700
b	0.280	0.380
c	0.080	0.150
D	0.750	0.850
E	1.100	1.300
E1	1.500	1.700
E2	0.200 REF	
L	0.010	0.070
θ	7° REF	

SOD-523焊盘设计参考 SOD-523 Suggested Pad Layout



Note:

1. Controlling dimension: in millimeters.
2. General tolerance: ± 0.05 mm.
3. The pad layout is for reference purposes only.